

Customer Quote 

Receiving Customer Order 

Contract Review 

Enter order in MRP System 

Engineering 

The cam-tool generation 

**Part 1. Before the Production**

# Raw Material Releasing

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graph TD; A[Raw Material Releasing] --> B[Preparing the Base Material]; A --> C[Circuit Pattern Generation]; A --> D[Etch the Circuit Pattern]; A --> E[Electrical Testing and Verification]; C --> F[Screen Printing]; C --> G[Photo Imaging]; D --> H[Drilling Processes]; D --> I[Through-hole Plating]; I --> J[Apply Cover lay or Covercoat]; J --> K[Cutting out the Flex]
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**Preparing the Base Material**

**Circuit Pattern Generation**

**Screen Printing**

**Photo Imaging**

**Etch the Circuit Pattern**

**Drilling Processes**

**Through-hole Plating**

**Apply Cover lay or Covercoat**

**Cutting out the Flex**

**Electrical Testing and Verification**

# PCB Fabrication

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graph TD; A[PCB Fabrication] --- B[The Follow-up]; B --- C[Electrical Test]; C --- D[Scoring (IF REQD)]; D --- E[Fabrication]; E --- F[Final Cleaning]; F --- G[Final Visual Inspection]; G --- H[QC And FAI Reporting]; H --- I[Packaging]; I --- J[Invoicing]; J --- K[Shipping];
```

The Follow-up

Electrical Test

Scoring (IF REQD)

Fabrication

Final Cleaning

Final Visual Inspection

QC And FAI Reporting

Packaging

Invoicing

Shipping